

(3.20 mm) .126"

XCede® HD POWER MODULE

HPTS SERIES

SPECIFICATIONS

Insulator Material:

Black, PPS

Contact Material:

Copper Alloy

Plating:

Sn or Au over

50 μ " (1.27 μ m) Ni**Operating Temp Range:** Testing Now!**Current Rating:**

12.3 A per pin

(2 pins powered)

RoHS Compliant:

Yes

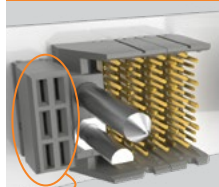
Mates with:

BSP

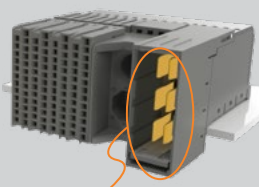
(See HDTF for more information)

Mounts individually to backplane

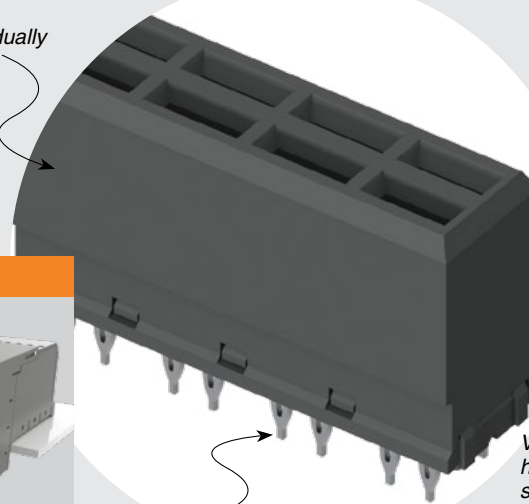
APPLICATION



HPTS Series individually mounts to backplane



Mates with integrated receptacle (BSP Series) configured with power module



Press-fit tails

Variety of body heights to match signal module pair count

TOOLING

- For press-fit extraction and insertion tool options, visit www.samtec.com/tooling

HPTS

BODY
HEIGHT

PLATING

D

ORIENTATION

(Based on pair count of signal modules (HDTF Series))

-3

= For use with 3 pair HDTF Series

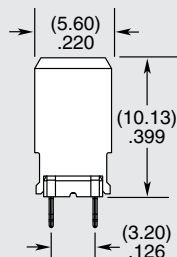
-4

= For use with 4 pair HDTF Series

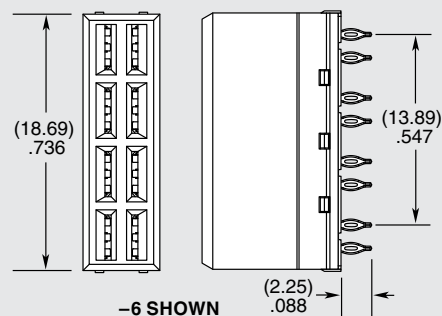
-6

= For use with 6 pair HDTF Series

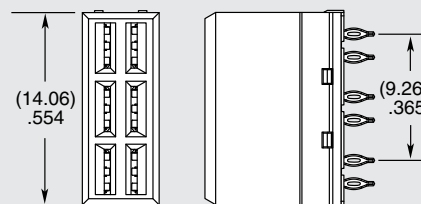
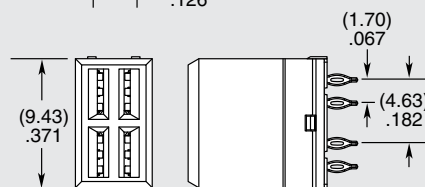
-S

= 30 μ " (0.76 μ m)
Gold in contact area,
Matte Tin on tail-VT
= Vertical

-3 SHOWN



-6 SHOWN



-4 SHOWN

Note:
XCede® is a registered trademark of Amphenol.

Due to technical progress, all designs, specifications and components are subject to change without notice.

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.